

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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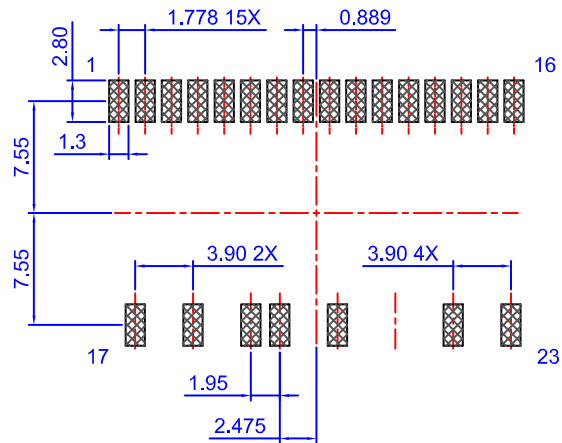
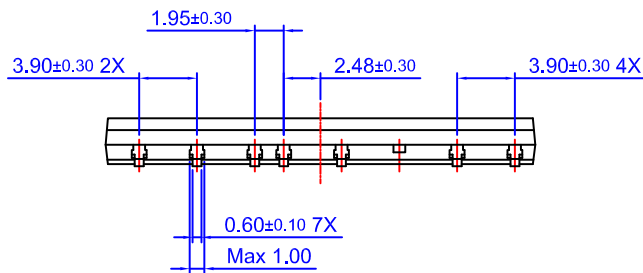
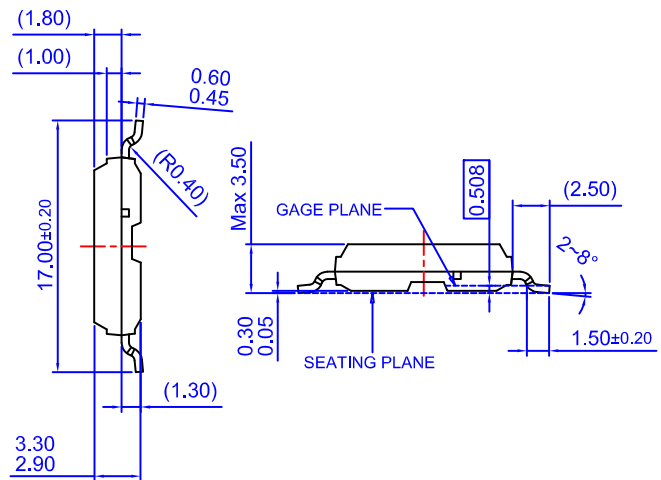
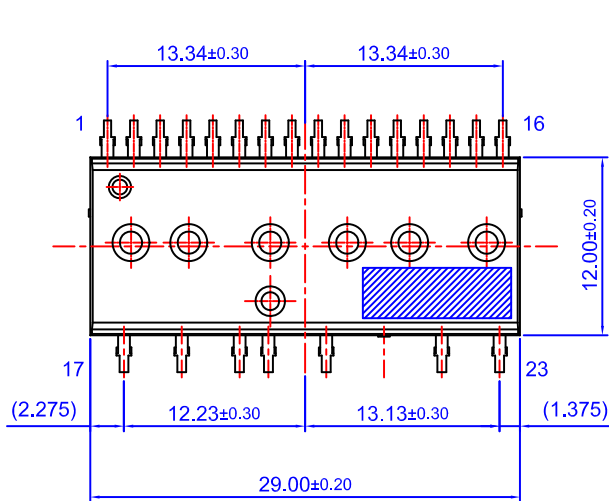
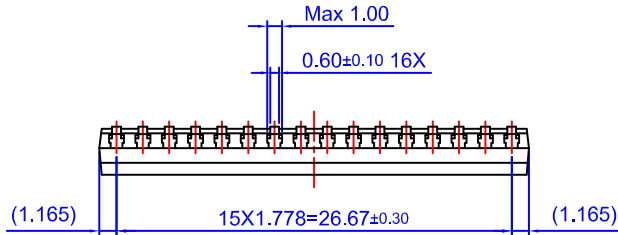


SPM5D-023 / SPM5_SPM23-BA SMD TYPE

CASE MODEH

ISSUE O

DATE 31 JAN 2017



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE

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